

ALPHA OM-5100 FINE PITCH SOLDER PASTE

Cookson Electronics Assembly Material ALPHA OM-5100

SMT

ALPHA OM-5100	0.4mm (16 mil)	0.3mm (12 mil)
18°C 28°C	150 mm/sec (6 inch/sec)	

OSP
90%

: 62Sn/36Pb/2Ag	63Sn/37Pb
: : 3	, (25-45 µm) IPC J-STD-086)
: : 500	, 6" 12"

Assembly Materials	SMT	0.1 mm (4 mil)	0.15 mm (6 mil)	Cookson Electronics
ALPHA OM-5100		0.3 mm (12 mil)		150 mm/sec (6 in./sec)

ALPHA OM-5100

MSDS

ALPHA OM-5100 3-7°C (35 - 45°F)

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ALPHA OM-5100		
	REL-0 = J-STD () (L)	IPC J-STD-004
	()	IPC J-STD-004
	()	IPC J-STD-004
SIR (IPC 7 @ 85° C/85% RH)	2.5 x 10 ⁹ ohms	, IPC J-STD-004 = 1 x 10 ⁹ ohm,
SIR (Bellcore 96 @ 35° C/85% RH)	9.78 x 10 ¹² ohms	, Bellcore GR78-CORE = 1 x 10 ¹¹ ohm]
(Bellcore 500 @ 65° C/85° RH)	8.9 x 10 ⁹ ohms, 2.85 x 10 ¹¹ ohms	, Bellcore GR78-CORE 62Sn/36Pb/2Ag = > /10]
	90% , #3	
(24)	25%, 50% 75% 1g/mm ²	63Sn/37Pb IPC J-STD-005
	90% , M14,	Malcom ; J-STD-005
	< 10 (62Sn/36Pb/2Ag, 63Sn/37Pb)	IPC J-STD-005
	> 8	@ 50% RH, 23°C (74°F) IPC J-STD-005

Alu-Damp is a registered trademark of Cookson Equipment Group. Hyflex™ is registered trademark of Petrobras.

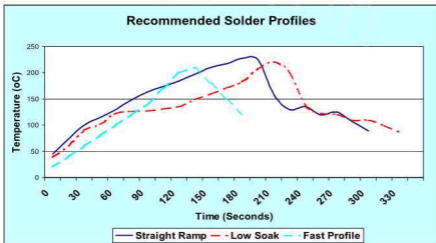
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ALPHA OM-5100		
		(#1)
<ul style="list-style-type: none"> • @ 3-7°C (35-45°F) • • 8 18°C (64°F) 28°C (82°F) • 	_____: Cookson Electronics Assembly Material ALPHA CUT ALPHA FORM 0.1 mm (4 mil) 0.15 mm (6 mil) _____: _____: 0.15 0.3 kg cm (0.8-1.5 lbs.) _____: 25 mm 150 mm/sec (1 to 6 inches/sec) _____: 1.5 - 2.0 cm (0.6-0.8 inch) 1 cm(0.4 in.) _____: ALPHA OM-5100 MPM RheoPump™ DEK Proflow	_____: _____: _____: (Sn 62/ 36Pb/ 2Ag _____): _____: 0.8°C 1.2°C per second 30 90 sec 210 to 220°C _____: - 60-120°C/min 140-160°C - 140-160°C 0-1.0 minutes, - 60-120°C/min 210-220°C - 178°C = 30-90 sec. - 60-150°C/min
		<ul style="list-style-type: none"> • ALPHA OM-5100 ALPHA Bioact™ SC-10 & SC-10E Hydrex™ SP Cookson Electronics Assembly Materials

Figure #1: Typical Reflow Profiles



RheoPump is a registered trademark of Cookson Equipment Group. Hydrex™ is registered trademark of Electrojet.

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